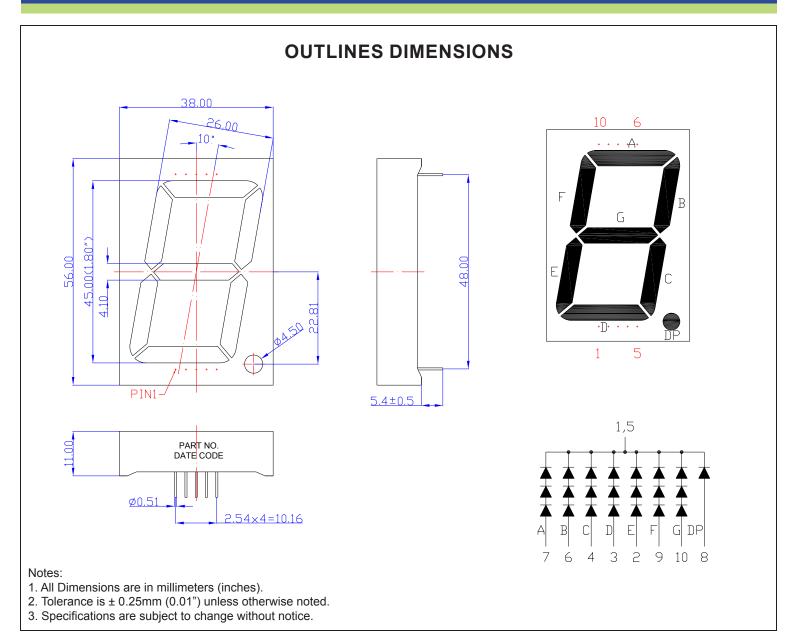


SPECIFICATIONS CDSC18W2W



| Part Number | Chip Material | Color of Emission | Lens Type | Description | |
|-------------|---------------|-------------------|---------------|----------------|--|
| CDSC18W2W | InGaN | White | White Segment | Common Cathode | |





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

| Parameter | Symbol | Max Rating | Unit | | | | |
|--|--------|------------|------|--|--|--|--|
| Power Dissipation | Pb | 78 | mW | | | | |
| Pulse Forward Current | lFP | 60 | mA | | | | |
| Continuous Forward Current | lF | 20 | mA | | | | |
| Reverse Voltage Segment | VR | 5 | V | | | | |
| Operating Temperature Range | Topr | -25~+85 | °C | | | | |
| Storage Temperature Range | Тѕтс | -25~+85 | °C | | | | |
| IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec | | | | | | | |

OPTICAL-ELECTRICAL CHARACTERISTICS

 $(TA=25^{\circ}C)$

| Darameter | Symbol | Toot Condition | Value | | | Linit |
|--------------------------------|--------|----------------------|-------|-------|-----|-------|
| Parameter | | Test Condition | Min | Тур | Max | Unit |
| Luminous Intensity per segment | lv | I⊧ = 5mA | - | 180 | - | mcd |
| Forward Voltage per segment | VF | I _F = 5mA | - | 8.7 | - | V |
| Reverse Leakage Current | lR | V _R = 5V | - | - | 10 | μΑ |
| Chromaticity Coordinates | X | I _F = 5mA | - | 0.285 | 1 | - |
| Chromaticity Coordinates | λD | I _F = 5mA | - | 0.275 | - | - |
| Spectral Radiation Bandwidth | Δλ | I _F = 5mA | - | 30 | - | nm |





OPTICAL CHARACTERISTIC CURVES

(25 °C Free Air Temperature Unless Otherwise Specified)

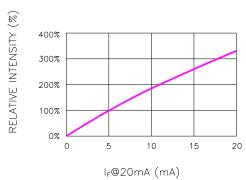
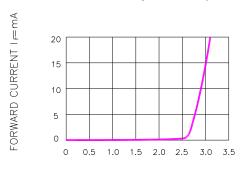
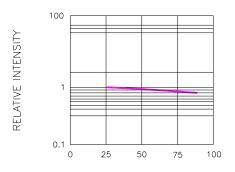


Fig. 1 RELATIVE INTENSITY VS. FORWARD CURRENT



FORWARD VOLTAGE (V)
Fig.2 FORWARD CURRENT VS. FORWARD VOLTAGE



LEAD TEMPERATURE(*C)
Fig.3 RELATIVE INTENSITY VS.LEAD TEMPERATURE
(PULSED 20 mA; 300us
PULSE,10ms PERIOD)

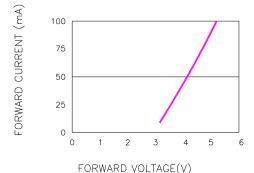


Fig.4 PEAK FORWARD VOLTAGE VS.FORWARD(100us TEST PULSE, 1% DUTY CYCLE)

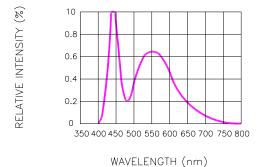
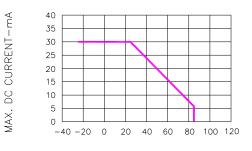


Fig.4 RELATIVE INTENSITY VS. WAVELENGTH



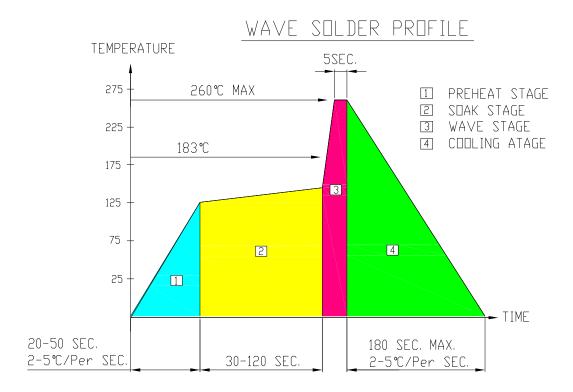
AMBIENT TEMPERATURE (TA)—°C
Fig.7 MAX. ALLOWABLE DC CURRENT
VS. AMBIENT TEMPERATURE

RoHS Compliant



SOLDERING CONDITIONS - DISPLAY TYPE LED

RECOMMEND SOLDERING PROFILE



Note:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 225°C for 3 sec (5 sec max)
- No more than one wave soldering pass

SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦3 sec under 350°C. The head of soldering iron cannot touch copper foil.

